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- Very Low Dropout Voltage, Less Than 0.6 V at 750 mA
- Low Quiescent Current
- TTL- and CMOS-Compatible Enable on TL751M Series
- 60-V Load-Dump Protection
- Overvoltage Protection
- Internal Thermal Overload Protection
- Internal Overcurrent-Limiting Circuitry

#### description

The TL750M and TL751M series are low-dropout positive voltage regulators specifically designed for battery-powered systems. The TL750M and TL751M series incorporate onboard overvoltage and current-limiting protection circuitry to protect the devices and the regulated system. Both series are fully protected against 60-V load-dump and reverse-battery conditions. Extremely low quiescent current, even during full-load conditions, makes the TL750M and TL751M series ideal for standby power systems.

The TL750M and TL751M series offers 5-V, 8-V, 10-V, and 12-V options. The TL751M series has the addition of an enable (ENABLE) input. The ENABLE input gives the designer complete control over power up, allowing sequential power up or emergency shutdown. When ENABLE is high, the regulator output is placed in the high-impedance state. The ENABLE input is TTL- and CMOS-compatible.

The TL750MxxC and TL751MxxC are characterized for operation over the virtual junction temperature range 0°C to 125°C.

			AVAILABLE OF	TIONS		
			PACKAGE	D DEVICES	-	
Тյ	V <sub>O</sub> TYP (V)	HEAT-SINK MOUNTED (3-PIN) (KC)	PLASTIC FLANGE MOUNT (KTE)	PLASTIC FLANGE MOUNT (KTG)	PLASTIC FLANGE MOUNT (KTP)	CHIP FORM (Y)
	5	TL750M05CKC	TL750M05CKTE	TL751M05CKTG	TL750M05CKTPR	TL750M05Y
0°C to 125°C	8	TL750M08CKC	TL750M08CKTE	TL751M08CKTG	TL750M08CKTPR	TL750M08Y
0 0 10 125 0	10	TL750M10CKC	TL750M10CKTE	TL751M10CKTG	TL750M10CKTPR	TL750M10Y
	12	TL750M12CKC	TL750M12CKTE	TL751M12CKTG	TL750M12CKTPR	TL750M12Y

AVAILABLE OPTIONS

The KTE and KTG packages are available taped and reeled. The KTP is only available taped and reeled. Add the suffix R to device type (e.g., TL750M05CKTER). Chip forms are tested at 25°C.



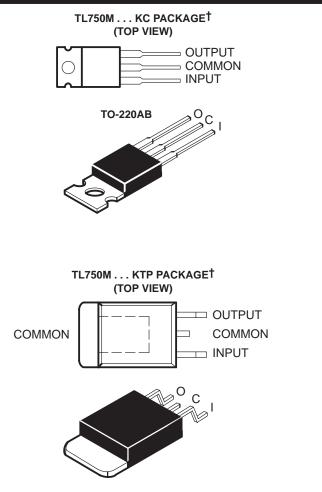
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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



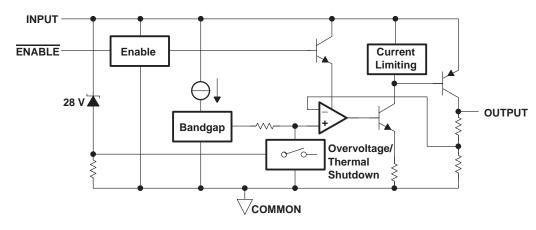
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 $^{\dagger}$  The common terminal is in electrical contact with the mounting base. NC – No internal connection

## TL751Mxx functional block diagram



DEVICE COMPONENT COUNT					
Transistors	46				
Diodes	14				
Resistors	44				
Capacitors	4				
JFETs	1				
Tunnels (emitter R)	2				

TL750M ... KTE PACKAGE<sup>†</sup>

(TOP VIEW)

TL751M ... KTG PACKAGE<sup>†</sup>

(TOP VIEW)

III NC

N C

Е

<sup>⊥⊥</sup> INPUT <sup>⊥⊥</sup> ENABLE

 $extsf{m}$  Common  $extsf{m}$  INPUT

o c



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#### absolute maximum ratings over virtual junction temperature range (unless otherwise noted)<sup>†</sup>

Continuous input voltage Transient input voltage (see Figure 3) Continuous reverse input voltage Transient reverse input voltage: $t = 100 \text{ ms}$ Package thermal impedance, $\theta_{JA}$ (see Notes 1 and 2	): KC package . KTE package KTG package KTP package	
Virtual junction temperature range, T <sub>J</sub> Lead temperature 1,6 mm (1/16 inch) from case for 1 Storage temperature range, T <sub>stg</sub>	0 seconds	260°C

<sup>+</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. Maximum power dissipation is a function of  $T_J(max)$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(max) T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can impact reliability. Due to variation in individual device electrical characteristics and thermal resistance, the built-in thermal overload protection may be activated at power levels slightly above or below the rated dissipation.
  - 2. The package thermal impedance is calculated in accordance with JESD 51.

#### recommended operating conditions

		MIN	MAX	UNIT
	TL75xM05	6	26	
Input voltage range, V <sub>I</sub>	TL75xM08	9	26	v
	TL75xM10	11	26	v
	TL75xM12	13	26	
High-level ENABLE input voltage, VIH	TL751Mxx	2	15	V
Low-level ENABLE input voltage, VIL	TL751Mxx	0	0.8	V
Output current range, IO	TL75xMxxC		750	mA
Operating virtual junction temperature range, T <sub>J</sub>	TL75xMxxC	0	125	°C

### electrical characteristics, $V_I = 14 V$ , $I_O = 300 mA$ , $T_J = 25^{\circ}C$

PARAMETER		TL751MXXX		
	MIN TYP MAX	UNIT		
Response time, ENABLE to output		50		μs



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# electrical characteristics, V<sub>I</sub> = 14 V, I<sub>O</sub> = 300 mA, ENABLE at 0 V for TL751M05, T<sub>J</sub> = 25°C (unless otherwise noted) (see Note 3)

PARAMETER	TEST CONDITIONS			TL750M05C TL751M05C			
			MIN	TYP	MAX		
Output voltage			4.95	5	5.05	V	
	$T_J = 0^{\circ}C$ to $125^{\circ}C$		4.9		5.1	v	
	V <sub>I</sub> = 9 V to 16 V,	I <sub>O</sub> = 250 mA		10	25		
Input voltage regulation	V <sub>I</sub> = 6 V to 26 V,	I <sub>O</sub> = 250 mA		12	50	mV	
Ripple rejection	V <sub>I</sub> = 8 V to 18 V,	f = 120 Hz	50	55		dB	
Output voltage regulation	I <sub>O</sub> = 5 mA to 750 mA			20	50	mV	
Drepout voltogo	$I_{O} = 500 \text{ mA}$ $I_{O} = 750 \text{ mA}$				0.5	V	
Dropout voltage					0.6	v	
Output noise voltage	f = 10 Hz to 100 kHz			500		μV	
Diag surgest	I <sub>O</sub> = 750 mA I <sub>O</sub> = 10 mA			60	75		
Bias current					5	mA	
Bias current (TL751M05C and TL751M05Q only)	ENABLE V <sub>IH</sub> ≥ 2 V				200	μA	

NOTE 3: Pulse-testing techniques maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.1-µF capacitor across the input and a 10-µF tantalum capacitor on the output, with equivalent series resistance within the guidelines shown in Figure 3.

# electrical characteristics, V<sub>I</sub> = 14 V, I<sub>O</sub> = 300 mA, ENABLE at 0 V for TL751M08, T<sub>J</sub> = 25°C (unless otherwise noted) (see Note 3)

PARAMETER	TEST CONDITIONS	TL750M08C TL751M08C			UNIT
		MIN	TYP	MAX	
Output voltage		7.92	8	8.08	V
Odiput voltage	$T_J = 0^{\circ}C$ to $125^{\circ}C$	7.84		8.16	v
Input voltage regulation	$V_{I} = 10 V$ to 17 V, $I_{O} = 250 mA$		12	40	mV
Input voltage regulation	$V_{I} = 9 V \text{ to } 26 V,$ $I_{O} = 250 \text{ mA}$		15	68	mv
Ripple rejection	$V_{I} = 11 V \text{ to } 21 V$ , $f = 120 \text{ Hz}$	50	55		dB
Output voltage regulation	I <sub>O</sub> = 5 mA to 750 mA		24	80	mV
Dropout voltage	I <sub>O</sub> = 500 mA			0.5	V
Dropout voltage	I <sub>O</sub> = 750 mA			0.6	v
Output noise voltage	f = 10 Hz to 100 kHz		500		μV
Rice current	I <sub>O</sub> = 750 mA		60	75	
Bias current	I <sub>O</sub> = 10 mA			5	mA
Bias current (TL751Mxx only)	ENABLE V <sub>IH</sub> ≥ 2 V			200	μA

NOTE 3: Pulse-testing techniques maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.1-µF capacitor across the input and a 10-µF tantalum capacitor on the output, with equivalent series resistance within the guidelines shown in Figure 3.



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# electrical characteristics, V<sub>I</sub> = 14 V, I<sub>O</sub> = 300 mA, ENABLE at 0 V for TL751M10, T<sub>J</sub> = 25°C (unless otherwise noted) (see Note 3)

PARAMETER	TEST CONDITIONS	TL750M10C TL751M10C			UNIT
		MIN	TYP	MAX	
Output voltage		9.9	10	10.1	V
Output voltage	$T_J = 0^{\circ}C$ to $125^{\circ}C$	9.8		10.2	v
Input voltage regulation	$V_{I} = 12 \text{ V to } 18 \text{ V},$ $I_{O} = 250 \text{ mA}$		15	43	mV
Input voltage regulation	$V_{I} = 11 V \text{ to } 26 V$ , $I_{O} = 250 \text{ mA}$		20	75	IIIV
Ripple rejection	V <sub>I</sub> = 13 V to 23 V, f = 120 Hz	50	55		dB
Output voltage regulation	$I_{O} = 5 \text{ mA to } 750 \text{ mA}$		30	100	mV
Dropout valtage	I <sub>O</sub> = 500 mA			0.5	V
Dropout voltage	I <sub>O</sub> = 750 mA			0.6	v
Output noise voltage	f = 10 Hz to 100 kHz		1000		μV
Diag gurrant	I <sub>O</sub> = 750 mA		60	75	A
Bias current	I <sub>O</sub> = 10 mA			5	mA
Bias current (TL751Mxx only)	ENABLE V <sub>IH</sub> ≥ 2 V			200	μA

NOTE 3: Pulse-testing techniques maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.1-µF capacitor across the input and a 10-µF tantalum capacitor on the output, with equivalent series resistance within the guidelines shown in Figure 3.

# electrical characteristics, V<sub>I</sub> = 14 V, I<sub>O</sub> = 300 mA, ENABLE at 0 V for TL751M12, T<sub>J</sub> = 25°C (unless otherwise noted) (see Note 3)

PARAMETER	TEST CONDITIONS	TL750M12C TL751M12C			UNIT
		MIN	TYP	MAX	
Output voltage		11.88	12	12.12	V
Output voltage	$T_J = 0^{\circ}C$ to $125^{\circ}C$	11.76		12.24	v
Input voltage regulation	$V_{I} = 14 V \text{ to } 19 V$ , $I_{O} = 250 \text{ mA}$		15	43	mV
Input voltage regulation	$V_{I} = 13 V \text{ to } 26 V,$ $I_{O} = 250 \text{ mA}$		20	78	IIIV
Ripple rejection	V <sub>I</sub> = 13 V to 23 V, f = 120 Hz	50	55		dB
Output voltage regulation	$I_{O} = 5 \text{ mA to } 750 \text{ mA}$		30	120	mV
Dropout voltage	I <sub>O</sub> = 500 mA			0.5	V
Diopour voitage	I <sub>O</sub> = 750 mA			0.6	v
Output noise voltage	f = 10 Hz to 100 kHz		1000		μV
Bias current	I <sub>O</sub> = 750 mA		60	75	~^^
Blas current	I <sub>O</sub> = 10 mA			5	mA
Bias current (TL751Mxx only)	ENABLE $V_{IH} \ge 2 V$			200	μΑ

NOTE 3: Pulse-testing techniques maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.1-µF capacitor across the input and a 10-µF tantalum capacitor on the output, with equivalent series resistance within the guidelines shown in Figure 3.



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# electrical characteristics, $V_I = 14 V$ , $I_O = 300 mA$ , ENABLE at 0 V, $T_J = 25^{\circ}C$ (unless otherwise noted) (see Note 3)

PARAMETER	TEST CO	TL	TL750M05Y			
FARAMETER	TEST CONDITIONS MIN TY		TYP	MAX	UNIT	
Output voltage				5		V
	V <sub>I</sub> = 9 V to 16 V,	I <sub>O</sub> = 250 mA		10		mV
Input voltage regulation	$V_{I} = 6 V \text{ to } 26 V,$	I <sub>O</sub> = 250 mA		12		IIIV
Ripple rejection	V <sub>I</sub> = 8 V to 18 V,	f = 120 Hz		55		dB
Output voltage regulation	$I_{O} = 5 \text{ mA to } 750 \text{ mA}$			20		mV
Output noise voltage	f = 10 Hz to 100 kHz			500		μV
Bias current	I <sub>O</sub> = 750 mA			60		mA

NOTE 3: Pulse-testing techniques maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.1-μF capacitor across the input and a 10-μF tantalum capacitor on the output, with equivalent series resistance within the guidelines shown in Figure 3.

# electrical characteristics, $V_I = 14 V$ , $I_O = 300 mA$ , ENABLE at 0 V, $T_J = 25^{\circ}C$ (unless otherwise noted) (see Note 3)

PARAMETER	TEST CO	TL	UNIT			
PARAMETER	TEST CO	TEST CONDITIONS			MAX	UNIT
Output voltage				8		V
	V <sub>I</sub> = 10 V to 17 V,	I <sub>O</sub> = 250 mA		12		mV
Input voltage regulation	V <sub>I</sub> = 9 V to 26 V,	I <sub>O</sub> = 250 mA		15		IIIV
Ripple rejection	V <sub>I</sub> = 11 V to 21 V,	f = 120 Hz		55		dB
Output voltage regulation	$I_{O} = 5 \text{ mA to } 750 \text{ mA}$			24		mV
Output noise voltage	f = 10 Hz to 100 kHz			500		μV
Bias current	I <sub>O</sub> = 750 mA			60		mA

NOTE 3: Pulse-testing techniques maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.1-μF capacitor across the input and a 10-μF tantalum capacitor on the output, with equivalent series resistance within the guidelines shown in Figure 3.

# electrical characteristics, $V_I = 14 V$ , $I_O = 300 mA$ , ENABLE at 0 V, $T_J = 25 °C$ (unless otherwise noted) (see Note 3)

PARAMETER	TEST CO	TL	UNIT			
PARAMETER	TEST CO	MIN	TYP	MAX	UNIT	
Output voltage				10		V
Input voltage regulation	VI = 12 V to 18 V,	I <sub>O</sub> = 250 mA		15		mV
Input voltage regulation	V <sub>I</sub> = 11 V to 26 V,	I <sub>O</sub> = 250 mA		20		IIIV
Ripple rejection	V <sub>I</sub> = 13 V to 23 V,	f = 120 Hz		55		dB
Output voltage regulation	$I_{O} = 5 \text{ mA to } 750 \text{ mA}$			30		mV
Output noise voltage	f = 10 Hz to 100 kHz			1000		μV
Bias current	I <sub>O</sub> = 750 mA			60		mA

NOTE 3: Pulse-testing techniques maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.1-μF capacitor across the input and a 10-μF tantalum capacitor on the output, with equivalent series resistance within the guidelines shown in Figure 3.



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# TL751M12Y electrical characteristics, $V_I = 14$ V, $I_O = 300$ mA, ENABLE at 0 V, $T_J = 25^{\circ}C$ (unless otherwise noted) (see Note 3)

PARAMETER	TEST CONDITIONS			TL750M12Y			
				TYP	MAX	UNIT	
Output voltage				12		V	
Input voltage regulation	V <sub>I</sub> = 14 V to 19 V,	I <sub>O</sub> = 250 mA		15		mV	
	$V_{I} = 13 V \text{ to } 26 V,$	I <sub>O</sub> = 250 mA		20		mv	
Ripple rejection	V <sub>I</sub> = 13 V to 23 V,	f = 120 Hz		55		dB	
Output voltage regulation	$I_{O} = 5 \text{ mA to } 750 \text{ mA}$			30		mV	
Output noise voltage	f = 10 Hz to 100 kHz			1000		μV	
Bias current	I <sub>O</sub> = 750 mA			60		mA	

NOTE 3: Pulse-testing techniques maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.1-µF capacitor across the input and a 10-µF tantalum capacitor on the output, with equivalent series resistance within the guidelines shown in Figure 3.

### PARAMETER MEASUREMENT INFORMATION

The TL751Mxx is a low-dropout regulator. This means that the capacitance loading is important to the performance of the regulator because it is a vital part of the control loop. The capacitor value and the equivalent series resistance (ESR) both affect the control loop and must be defined for the load range and the temperature range. Figures 1 and 2 can establish the capacitance value and ESR range for the best regulator performance.

Figure 1 shows the recommended range of ESR for a given load with a 10- $\mu$ F capacitor on the output. This figure also shows a maximum ESR limit of 2  $\Omega$  and a load-dependent minimum ESR limit.

For applications with varying loads, the lightest load condition should be chosen because it is the worst case. Figure 2 shows the relationship of the reciprocal of ESR to the square root of the capacitance with a minimum capacitance limit of 10  $\mu$ F and a maximum ESR limit of 2  $\Omega$ . This figure establishes the amount that the minimum ESR limit shown in Figure 1 can be adjusted for different capacitor values. For example, where the minimum load needed is 200 mA, Figure 2 suggests an ESR range of 0.8  $\Omega$  to 2  $\Omega$  for 10  $\mu$ F. Figure 2 shows that changing the capacitor from 10  $\mu$ F to 400  $\mu$ F can change the ESR minimum by greater than 3/0.5 (or 6). Therefore, the new minimum ESR value is 0.8/6 (or 0.13  $\Omega$ ). This allows an ESR range of 0.13  $\Omega$  to 2  $\Omega$ , achieving an expanded ESR range by using a larger capacitor at the output. For better stability in low-current applications, a small resistance placed in series with the capacitor (see Table 1) is recommended, so that ESRs better approximate those shown in Figures 1 and 2.

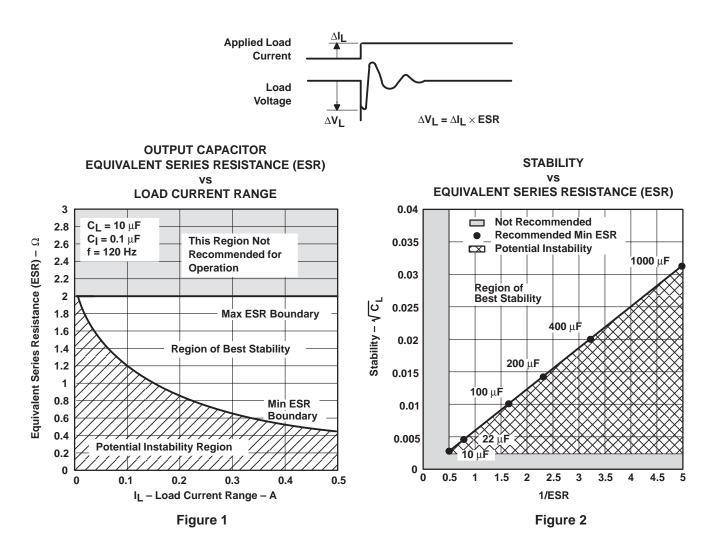


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### PARAMETER MEASUREMENT INFORMATION

Table 1. Compensation	n for Increased Sta	bility at Low Currents
-----------------------	---------------------	------------------------

MANUFACTURER	CAPACITANCE	ESR TYP	PART NUMBER	ADDITIONAL RESISTANCE
AVX	15 μF	0.9 Ω	TAJB156M010S	1 Ω
KEMET	33 μF	0.6 Ω	T491D336M010AS	0.5 Ω



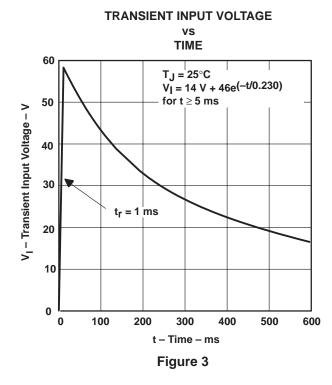


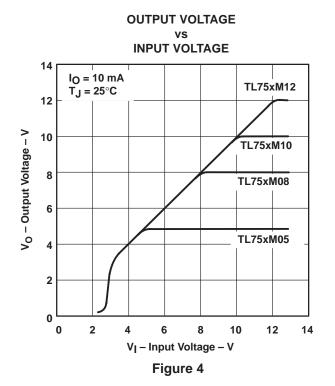
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### **TYPICAL CHARACTERISTICS**

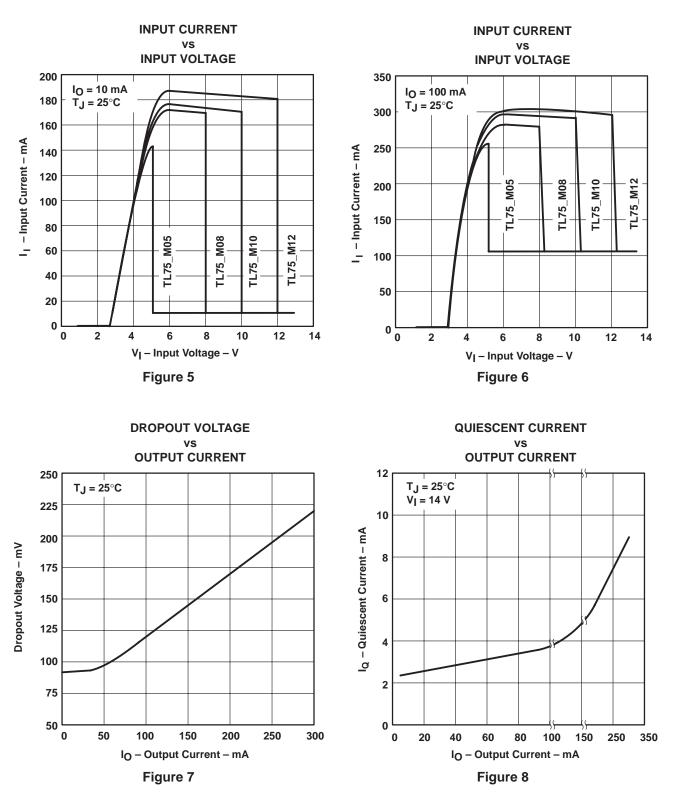
### **Table of Graphs**

		FIGURE
Transient input voltage vs Time	3	
Output voltage vs Input voltage	4	
Input current vs Input voltage	I <sub>O</sub> = 10 mA	5
input current vs input voltage	I <sub>O</sub> = 100 mA	6
Dropout voltage vs Output current	7	
Quiescent current vs Output curren	8	
Load transient response	9	
Line transient response	10	





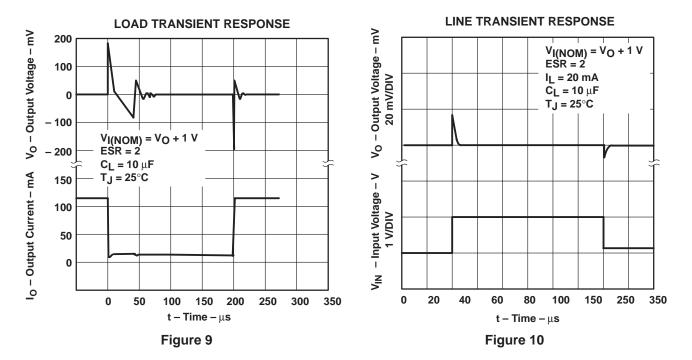
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### **TYPICAL CHARACTERISTICS**



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### **TYPICAL CHARACTERISTICS**



### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
TL750M05CKC	ACTIVE	TO-220	KC	3	50	TBD	Call TI	Level-1-220C-UNLIM
TL750M05CKTER	ACTIVE	PFM	KTE	3	2000	TBD	Call TI	Level-1-220C-UNLIM
TL750M05CKTPR	ACTIVE	PFM	KTP	2	3000	TBD	CU SNPB	Level-1-220C-UNLIM
TL750M10CKC	PREVIEW	TO-220	KC	3	50	TBD	Call TI	Call TI
TL750M12CKC	PREVIEW	TO-220	KC	3	50	TBD	Call TI	Call TI
TL751M05CKTGR	PREVIEW	PFM	KTG	5	2000	TBD	Call TI	Level-1-220C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

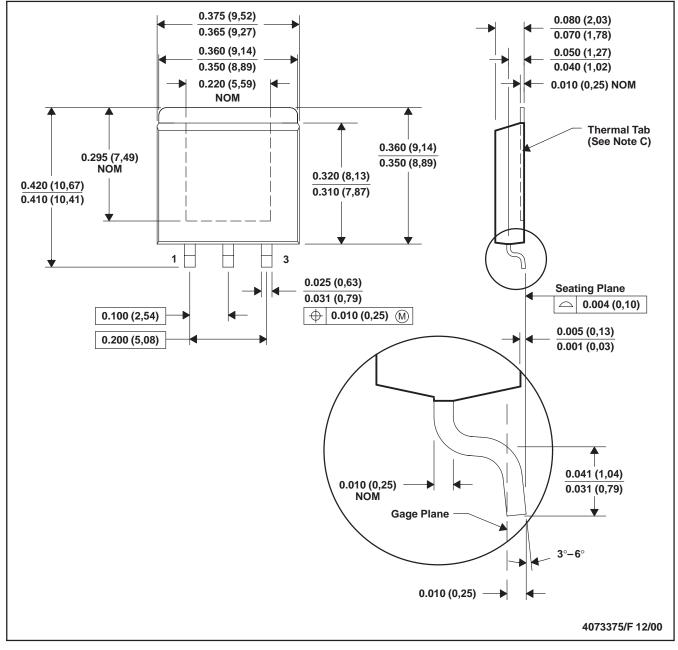
<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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MPFM001E - OCTOBER 1994 - REVISED JANUARY 2001

#### PowerFLEX<sup>™</sup> PLASTIC FLANGE-MOUNT



- NOTES: A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. The center lead is in electrical contact with the thermal tab.
  - D. Dimensions do not include mold protrusions, not to exceed 0.006 (0,15).
  - E. Falls within JEDEC MO-169

**KTE (R-PSFM-G3)** 

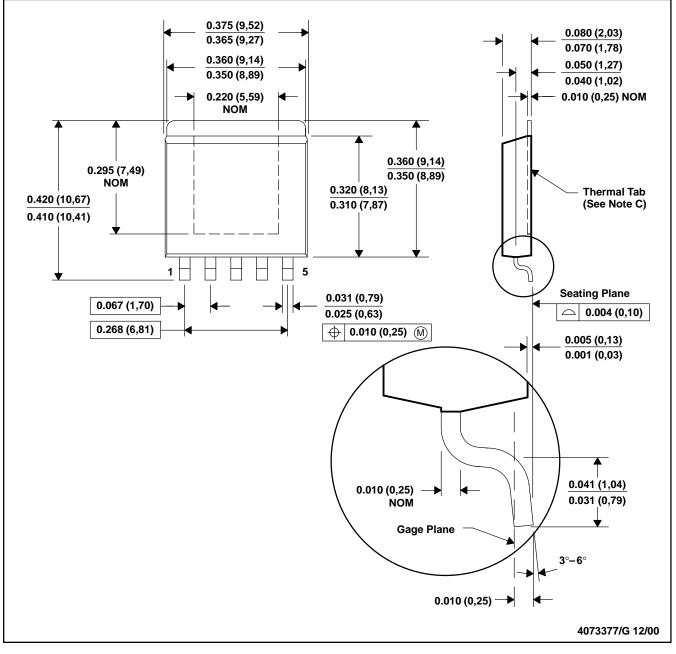
PowerFLEX is a trademark of Texas Instruments.

# **MECHANICAL DATA**

MPFM003F - OCTOBER 1994 - REVISED MARCH 2002

#### PowerFLEX<sup>™</sup> PLASTIC FLANGE-MOUNT PACKAGE

#### **KTG (R-PSFM-G5)**



- NOTES: A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. The center lead is in electrical contact with the thermal tab.
  - D. Dimensions do not include mold protrusions, not to exceed 0.006 (0,15).
  - E. FAIIs within JEDEC MO-169

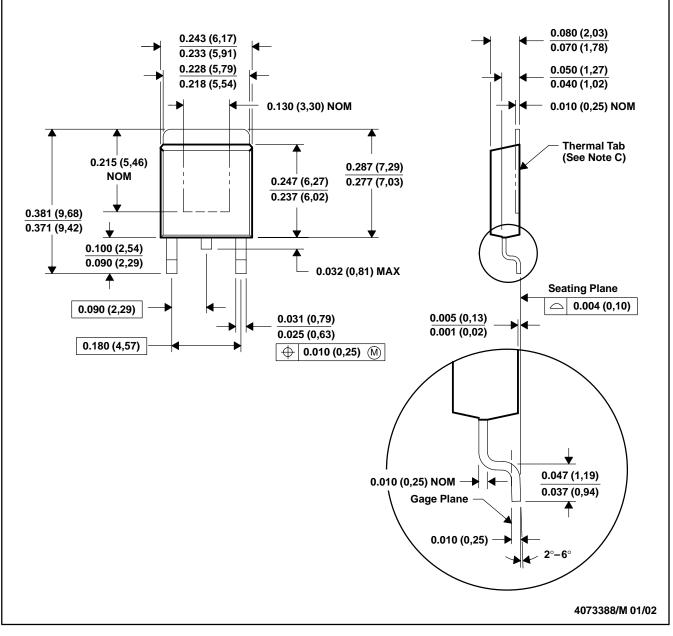
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# **MECHANICAL DATA**

MPSF001F - JANUARY 1996 - REVISED JANUARY 2002

#### KTP (R-PSFM-G2)

#### PowerFLEX<sup>™</sup> PLASTIC FLANGE-MOUNT PACKAGE

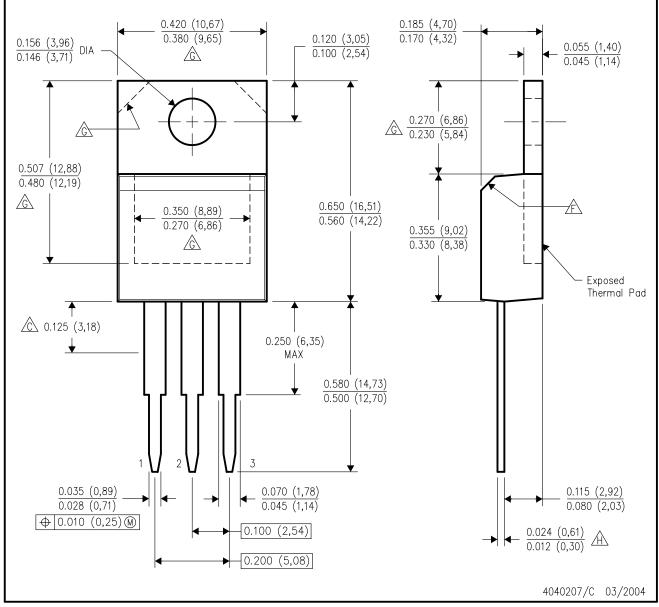


- NOTES: A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. The center lead is in electrical contact with the thermal tab.
  - D. Dimensions do not include mold protrusions, not to exceed 0.006 (0,15).
  - E. Falls within JEDEC TO-252 variation AC.

PowerFLEX is a trademark of Texas Instruments.

KC (R-PSFM-T3)

PLASTIC FLANGE-MOUNT PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Lead dimensions are not controlled within this area.

D. All lead dimensions apply before solder dip.

- E. The center lead is in electrical contact with the mounting tab.
- $\frown$  The chamfer is optional.
- A Thermal pad contour optional within these dimensions.
- $\triangle$  Falls within JEDEC TO-220 variation AB, except minimum lead thickness.



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